

44-V, 5.5-A, quad power half-bridge

Features

- Minimum input/output pulse width distortion
- 150 mΩ R_{dsON} complementary DMOS output stage
- CMOS compatible logic inputs
- Thermal protection
- Thermal warning output
- Undervoltage protection
- No power-on, power-off sequence required

Description

The STA510F is a monolithic, quad, half-bridge stage in multipower BCD technology. The device can be used as dual-bridge or reconfigured, by connecting the CONFIG pin to the Vdd pin, as single-bridge with double current capability, and as half-bridge (binary mode) with half current capability.



The device is particularly designed to make the output stage of a stereo all-digital high-efficiency (FFX) amplifier capable of delivering 100 W + 100 W output power into 8- Ω loads with THD = 10% and V_{cc} = 39 V. In single BTL configuration the device can deliver 200 W into a 4- Ω load with THD = 10% and V_{cc} = 39 V.

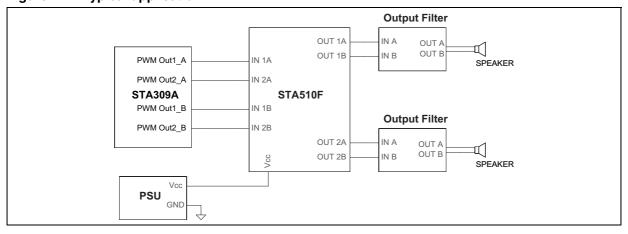
The device is fully compatible with the DDX[®] driver device.

The input pins have a threshold proportional to V_L pin voltage.

Table 1. Device summary

Order code	der code Operating temp. range Package			
STA510F	0° to 70° C	PowerSSO36 (slug up)	Tube	
STA510FTR	0° to 70° C	PowerSSO36 (slug up)	Tape & Reel	

Figure 1. Typical application



Pin description STA510F

1 Pin description

Figure 2. Pin connections (top view)

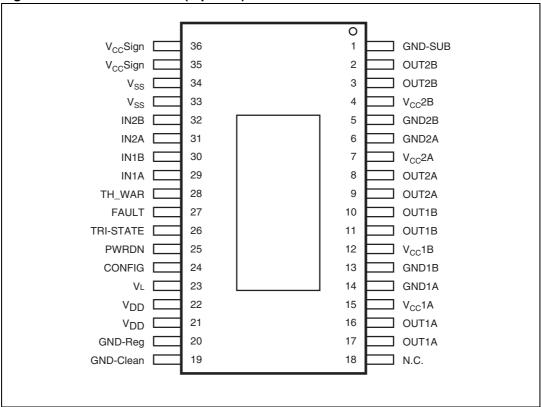


Table 2. Pin list

Pin	Name	Description	
1	GND-SUB	Substrate ground	
2, 3	OUT2B	Output half-bridge 2B	
4	Vcc2B	Positive supply	
5	GND2B	Negative supply	
6	GND2A	Negative supply	
7	Vcc2A	Positive supply	
8, 9	OUT2A	Output half-bridge 2A	
10, 11	OUT1B	Output half-bridge 1B	
12	Vcc1B	Positive supply	
13	GND1B	Negative supply	
14	GND1A	Negative supply	
15	Vcc1A	Positive supply	
16, 17	OUT1A	Output half-bridge 1A	

STA510F Pin description

Table 2. Pin list (continued)

Pin	Name	Description	
18	NC	Not connected	
19	GND-clean	Logical ground	
20	GND-Reg	Ground for regulator Vdd	
21, 22	Vdd	5-V regulator referred to ground	
23	V _L	High logical state setting voltage	
24	CONFIG	Configuration	
25	PWRDN	Standby	
26	TRI-STATE	Hi-Z	
27	FAULT	Fault pin advisor	
28	TH-WAR	Thermal warning advisor	
29	IN1A	Input of half-bridge 1A	
30	IN1B	Input of half-bridge 1B	
31	IN2A	Input of half-bridge 2A	
32	IN2B	Input of half-bridge 2B	
33, 34	Vss	5-V regulator referred to +Vcc	
35, 36	VCCSIGN	Signal positive supply	

Table 3. Pin values

Pin	Logical value	Device status		
FAULT (1)	0	Fault detected (short-circuit, or thermal)		
FAULI \ /	1	Normal operation		
TRI-STATE	0	All power stages in Hi-Z state		
THI-STATE	1	Normal operation		
PWRDN	0	Low-power mode		
LMUDIN	1	Normal operation		
THWAR (1)	0	Temperature of the IC = 130° C		
ITIWAN \ /	1	Normal operation		
	0	Normal operation		
CONFIG (2)	1	OUT1A = OUT1B, OUT2A = OUT2B (IF IN1A = IN1B and IN2A = IN2B)		

^{1.} The pin is open collector. To have the high logic value, it needs a pull-up resistor.

^{2.} CONFIG = 1 means connect pin 24 (CONFIG) to pins 21, 22 (Vdd).

2 Electrical specifications

2.1 Absolute maximum ratings

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	DC supply voltage (pin 4, 7, 12, 15)	44	٧
V _{max}	Maximum voltage on pins 23 to 32	5.5	V
ESD	Max ESD on pins (HBM)	±1000	٧
T _{op}	Operating temperature range	0 to 70	°C
T _{stg} , T _j	Storage and junction temperature	-40 to 150	° C

2.2 Thermal data

Table 5. Thermal data

Symbol	Parameter	Min	Тур	Max	Unit
T _{j-case}	Thermal resistance junction to case (thermal pad)		1	2.5	°C/W
T _{jSD}	Thermal shut-down junction temperature		150		° C
T _{warn}	Thermal warning temperature		130		° C
t _{hSD}	Thermal shutdown hysteresis		25		° C

2.3 Electrical specifications

The results in *Table 6* below are given for the conditions: $V_L=3.3~V,~Vcc=37~V$ and $T=25^{\circ}~C$ unless otherwise specified.

Table 6. Electrical specifications

Symbol	Parameter	Condition	Min	Тур	Max	Unit
R _{dsON}	Power Pchannel/Nchannel MOSFET RdsON	ld = 1 A		150	200	mΩ
I _{dss}	Power Pchannel/Nchannel leakage current				100	μΑ
g _N	Power Pchannel RdsON matching	Id = 1 A	95			%
g _P	Power Nchannel RdsON matching	Id = 1 A	95			%
Dt_s	Low current deadtime (static)	see test circuit Figure 3		10	20	ns
Dt_d	High current deadtime (dynamic)	L = 22 μ H, C = 470 nF, R _L = 8 Ω , Id = 4.5 A, see test circuit <i>Figure 4</i>			50	ns
t _{d ON}	Turn-on delay time	Resistive load			100	ns

Table 6. Electrical specifications (continued)

Symbol	Parameter	Condition	Min	Тур	Max	Unit
t _{d OFF}	Turn-off delay time	Resistive load			100	ns
t _r	Rise time	Resistive load, as Figure 4			25	ns
t _f	Fall time	Resistive load, as Figure 4			25	ns
V _{CC}	Supply voltage operating voltage		10		40	V
V _{IN-High}	High level input voltage		V _L /2 + 300mV			V
V _{IN-Low}	Low level input voltage				V _L /2 – 300mV	V
I _{IN-H}	High level input current	Pin voltage = V _L		1		μΑ
I _{IN-L}	Low level input current	Pin voltage = 0.3 V		1		μΑ
I _{PWRDN-H}	High level PWRDN pin input current	V _L = 3.3 V		35		μΑ
V _{Low}	Low logical state voltage (pins PWRDN, TRISTATE) (see <i>Table 7</i>)	V _L = 3.3 V			0.8	V
V_{High}	High logical state voltage (pins PWRDN, TRISTATE) (see <i>Table 7</i>)	V _L = 3.3 V	1.7			V
I _{VCC} -	Supply current from Vcc in power down	PWRDN = 0			3	mA
I _{FAULT}	Output current pins FAULT -TH-WARN when FAULT CONDITIONS	Vpin = 3.3 V		1		mA
I _{VCC-hiz}	Supply current from Vcc in tri-state	Pin TRI-STATE = 0		22		mA
l _{vcc}	Supply current from Vcc in operation both channel switching)	Input pulse width duty cycle = 50%, switching frequency = 384 kHz, no LC filters;		70		mA
I _{OUT-SH}	Overcurrent protection threshold Isc (short-circuit current limit)		5.5	7	9	Α
V _{UV}	Undervoltage protection threshold			7		٧
t _{pw_min}	Output minimum pulse width	No load	25		40	ns
		•				

Table 7. V_{low} , V_{high} threshold variation with V_L

V _L	V _{Low} max	V _{High} min	Unit
2.7	0.7	1.5	V
3.3	0.8	1.7	V
5	0.85	1.85	V

Table 8. Logic truth table

TRI-STATE	INxA	INxB	Q1	Q2	Q3	Q4	Output mode
0	х	х	OFF	OFF	OFF	OFF	Hi-Z
1	0	0	OFF	OFF	ON	ON	DUMP
1	0	1	OFF	ON	ON	OFF	NEGATIVE
1	1	0	ON	OFF	OFF	ON	POSITIVE
1	1	1	ON	ON	OFF	OFF	Not used

Figure 3. Test circuit for low current deadtime

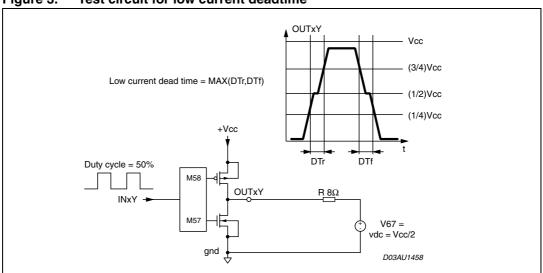
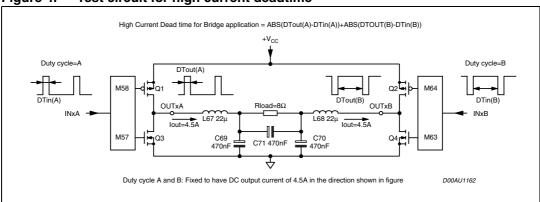


Figure 4. Test circuit for high current deadtime



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Figure 5. Typical quad half-bridge configuration giving 200 W per channel into 4 Ω speakers, 10% THD, V $_{\rm CC}$ = 39 V

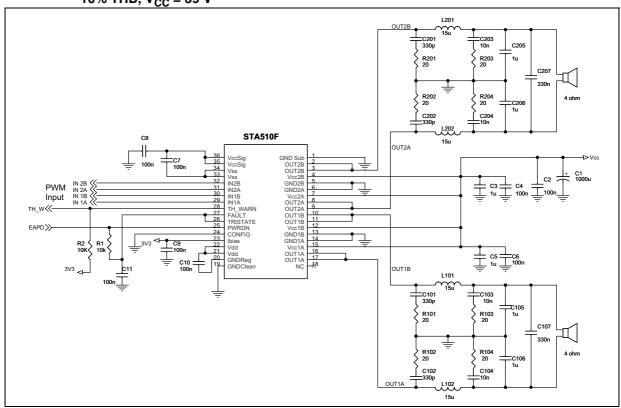
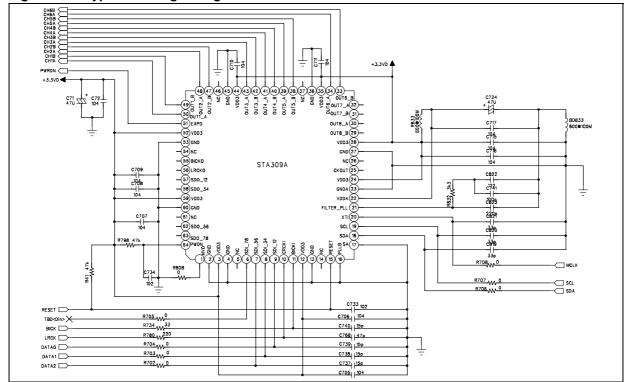


Figure 6. Typical driving configuration with STA309A



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Package information STA510F

3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 7. PowerSSO36 package dimensions

2.15 2.15				inch	
2.15	ΓΥP.	MAX.	MIN.	TYP.	MAX.
		2.47	0.084		0.097
_		2.40	0.084		0.094
0		0.075	0		0.003
0.18		0.36	0.007		0.014
0.23		0.32	0.009		0.012
10.10		10.50	0.398		0.413
7.4		7.6	0.291		0.299
- (0.50			0.020	
- 1	8.50			0.035	
	2.3			0.090	
		0.10			0.004
10.10		10.50	0.398		0.413
		0.40			0.016
0°		8°	0°		8°
0.55		0.85	0.022		0.033
	4.3			0.169	
		10° (max)		
	1.2			0.047	
	0.8			0.031	
	2.9			0.114	
	3.65			0.144	
	1.0			0.039	
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4 Trademarks and other acknowledgements

FFX is a STMicroelectronics proprietary digital modulation technology.

DDX is a registered trademark of Apogee Technology, Inc.

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Revision history STA510F

5 Revision history

Table 9. Document revision history

Date	Revision	Changes	
13-Dec-2007	1	Initial release.	
28-Jun-2011	2	Added part number STA510FTR to <i>Table 1: Device summary</i> Updated ECOPACK® text in <i>Section 3: Package information</i> Minor textual updates	
02-Sep-2011	3	Updated package to PowerSSO36 throughout datasheet Corrected typographical error in Features Updated Figure 1: Typical application Updated Figure 2: Pin connections (top view) Updated Figure 6: Typical driving configuration with STA309A Updated Figure 7: PowerSSO36 package dimensions	

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